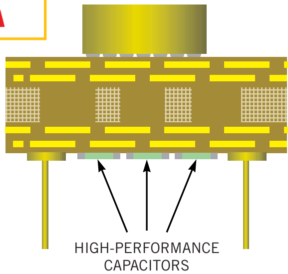
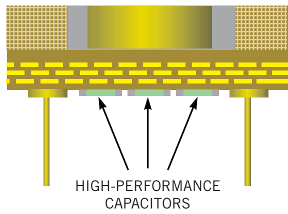
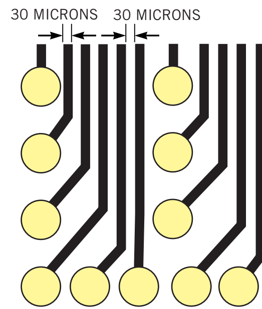
Figure A







Whereas conventional packages locate the die on top of the substrate (a), BBUL (bumpless-buildup-layer) packaging surrounds the die (b). Low height is one of the resulting advantages (c), along with more flexible die-to-substrate interconnection (d) (courtesy Intel).